

Customer No.: 31561
Docket No.: 10721-US-PA
Application No.: 10/711,280

REMARKS

Present Status of Application

Claims 1-2 and 5-8 were rejected under 35 U.S.C. §102(b) as being anticipated by Lin et al. (US Publication No. 2002/0127836 A1). Claims 3-4 were rejected under 35 U.S.C. §103(a) as being unpatentable over Lin et al..

Claim 8 has been amended for correcting informalities. No new matter has been added to the application by the amendments made to the specification, claims and drawings. This Amendment is promptly filed to place the above-captioned case in condition for allowance. After entering the amendments, a notice of allowance is respectfully solicited.

Discussion for 35 USC§102 and 103 rejections

Claims 1-2 and 5-8 were rejected under 35 U.S.C. §102(b) as being anticipated by Lin et al. (US Publication No. 2002/0127836 A1). Claims 3-4 were rejected under 35 U.S.C. §103(a) as being unpatentable over Lin et al. in view of the remarks cited in the 102 rejections.

The Applicant has carefully considered the remarks set forth in the Office Action.

The Office Action considered that Lin et al. substantially disclose the present invention.

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Applicants respectfully disagree and traverse the rejections based on at least the following reasons.

Applicants submit that the independent claim patently defines over the prior reference Lin for at least the reason that the cited art fails to disclose each and every feature as claimed in the present invention. Particularly, the reference Lin fails to teach or suggest at least the feature "providing a wafer having a plurality of LED chips thereon, wherein each of the LED chips comprises a plurality of electrodes".

Lin et al. discloses a conventional method for forming bumps (as shown in Fig. 5), including providing a contact pad 32 of a semiconductor surface 30 and depositing a passivation layer 34 over the semiconductor surface 30. The passivation layer 34 is patterned and a UBM layer 36 is formed. As taught by Lin's statement (paragraph [0055]), "Surface 30 will typically be the surface of a semiconductor substrate, the surface of an interconnect substrate and the like.".

The Office Action considered surface 30 of Lin's (referring to Lin's paragraph [0055]) as comparable to the wafer of this invention. However, the Office Action did not point out equivalent elements comparable to the LED chips and posts of this invention.

As discussed above, based on Lin's figures and contexts, it is obvious that surface 30 is not equivalent or comparable to "the wafer having a plurality of LED chips thereon" of this invention. Furthermore, nothing is mentioned or taught by Lin regarding the LED

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chips.

Accordingly, the independent claim 1 clearly distinguishes the present invention over the cited reference Lin.

Dependent claims 2 and 5-8 are submitted to be patentably distinguishable over the cited reference for at least the same reasons as independent claim 1, from which these claims respectively depend, as well as for the additional features that these claims recite.

As for dependent claims 3-4, Applicants respectfully submit that claims 3-4 patently define over the reference Lin for at least the above reasons, and should be allowed.

In view of the above amendment and discussions, reconsideration and withdrawal of these rejections under 35 USC 102(b) and 103(a) are respectfully requested.

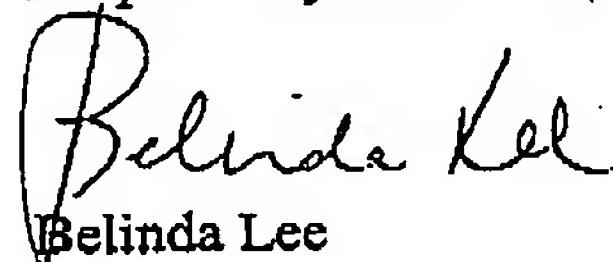
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CONCLUSION

In view of the foregoing, it is believed that all pending claims are in proper condition for allowance. If the Examiner believes that a telephone conference would expedite the examination of the above-identified patent application, the Examiner is invited to call the undersigned.

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Respectfully submitted,



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